

[***BUMP MANUFACTURING METHOD***]

Abstract of Disclosure

A method of forming bumps on the active surface of a silicon wafer. A first under-ball metallic layer is formed over the active surface of the wafer. A second under-ball metallic layer is formed over the first under-ball metallic layer. A portion of the second under-ball metallic layer is removed to expose the first under-ball metallic layer. A plurality of solder blocks is implanted over the second under-ball metallic layer. A reflux operation is conducted and then the exposed first under-ball metallic layer is removed so that only the first under-ball metallic layer underneath the second under-ball metallic layer remains.

Figures

[illegible]